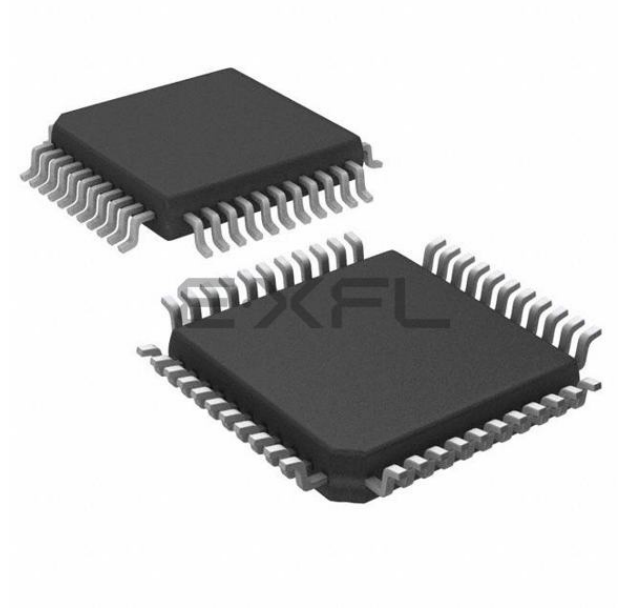

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	80C51
Core Size	8-Bit
Speed	40/30MHz
Connectivity	UART/USART
Peripherals	POR, WDT
Number of I/O	32
Program Memory Size	16KB (16K x 8)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-QFP
Supplier Device Package	44-VQFP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ts87c54x2-vie

Table 4-1. All SFRs with their address and their reset value

	Bit address-able	**Non Bit addressable**							
	0/8	1/9	2/A	3/B	4/C	5/D	6/E	7/F	
F8h									FFh
F0h	B 0000 0000								F7h
E8h									EFh
E0h	ACC 0000 0000								E7h
D8h									DFh
D0h	PSW 0000 0000								D7h
C8h	T2CON 0000 0000	T2MOD XXXX XX00	RCAP2L 0000 0000	RCAP2H 0000 0000	TL2 0000 0000	TH2 0000 0000			CFh
C0h									C7h
B8h	IP XX00 0000	SADEN 0000 0000							BFh
B0h	P3 1111 1111							IPH XX00 0000	B7h
A8h	IE 0X00 0000	SADDR 0000 0000							AFh
A0h	P2 1111 1111		AUXR1 XXXX 0XX0				WDTRST XXXX XXXX	WDTPRG XXXX X000	A7h
98h	SCON 0000 0000	SBUF XXXX XXXX							9Fh
90h	P1 1111 1111								97h
88h	TCON 0000 0000	TMOD 0000 0000	TL0 0000 0000	TL1 0000 0000	TH0 0000 0000	TH1 0000 0000	AUXR XXXX XXX0	CKCON XXXX XXX0	8Fh
80h	P0 1111 1111	SP 0000 0111	DPL 0000 0000	DPH 0000 0000				PCON 00X1 0000	87h
	0/8	1/9	2/A	3/B	4/C	5/D	6/E	7/F	

reserved

6. TS80C54/58X2 Enhanced Features

In comparison to the original 80C52, the TS80C54/58X2 implements some new features, which are:

- The X2 option.
- The Dual Data Pointer.
- The Watchdog.
- The 4 level interrupt priority system.
- The power-off flag.
- The ONCE mode.
- The ALE disabling.
- Some enhanced features are also located in the UART and the timer 2.

6.1 X2 Feature

The TS80C54/58X2 core needs only 6 clock periods per machine cycle. This feature called ”X2” provides the following advantages:

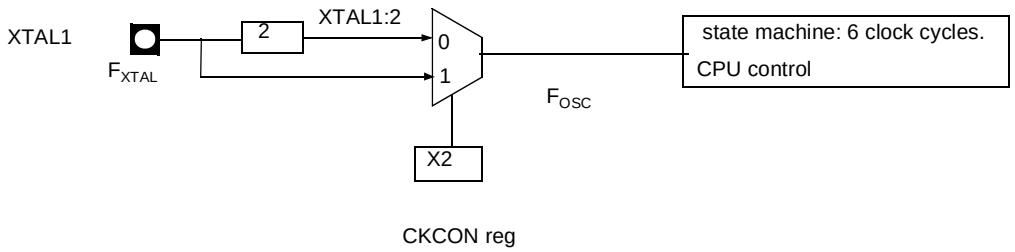
- Divide frequency crystals by 2 (cheaper crystals) while keeping same CPU power.
- Save power consumption while keeping same CPU power (oscillator power saving).
- Save power consumption by dividing dynamically operating frequency by 2 in operating and idle modes.
- Increase CPU power by 2 while keeping same crystal frequency.

In order to keep the original C51 compatibility, a divider by 2 is inserted between the XTAL1 signal and the main clock input of the core (phase generator). This divider may be disabled by software.

6.1.1 Description

The clock for the whole circuit and peripheral is first divided by two before being used by the CPU core and peripherals. This allows any cyclic ratio to be accepted on XTAL1 input. In X2 mode, as this divider is bypassed, the signals on XTAL1 must have a cyclic ratio between 40 to 60%. Figure 6-2. shows the clock generation block diagram. X2 bit is validated on XTAL1÷2 rising edge to avoid glitches when switching from X2 to STD mode. Figure 6-2. shows the mode switching waveforms.

Figure 6-1. Clock Generation Diagram



7.1 Application

Software can take advantage of the additional data pointers to both increase speed and reduce code size, for example, block operations (copy, compare, search ...) are well served by using one data pointer as a 'source' pointer and the other one as a "destination" pointer.

ASSEMBLY LANGUAGE

```
; Block move using dual data pointers
; Destroys DPTR0, DPTR1, A and PSW
; note: DPS exits opposite of entry state
; unless an extra INC AUXR1 is added
;
00A2                AUXR1 EQU 0A2H
;
0000 909000         MOV   DPTR,#SOURCE      ; address of SOURCE
0003 05A2           INC   AUXR1             ; switch data pointers
0005 90A000         MOV   DPTR,#DEST        ; address of DEST
0008                LOOP:
0008 05A2           INC   AUXR1             ; switch data pointers
000A E0             MOVX  A,@DPTR           ; get a byte from SOURCE
000B A3             INC   DPTR              ; increment SOURCE address
000C 05A2           INC   AUXR1             ; switch data pointers
000E F0             MOVX  @DPTR,A           ; write the byte to DEST
000F A3             INC   DPTR              ; increment DEST address
0010 70F6           JNZ   LOOP              ; check for 0 terminator
0012 05A2           INC   AUXR1             ; (optional) restore DPS
```

INC is a short (2 bytes) and fast (12 clocks) way to manipulate the DPS bit in the AUXR1 SFR. However, note that the INC instruction does not directly force the DPS bit to a particular state, but simply toggles it. In simple routines, such as the block move example, only the fact that DPS is toggled in the proper sequence matters, not its actual value. In other words, the block move routine works the same whether DPS is '0' or '1' on entry. Observe that without the last instruction (INC AUXR1), the routine will exit with DPS in the opposite state.

8. Timer 2

The timer 2 in the TS80C54/58X2 is compatible with the timer 2 in the 80C52.
It is a 16-bit timer/counter: the count is maintained by two eight-bit timer registers, TH2 and TL2, connected in cascade. It is controlled by T2CON register (See Table 8-1) and T2MOD register (See Table 8-2). Timer 2 operation is similar to Timer 0 and Timer 1. C/$\overline{T2}$ selects F_{OSC}/12 (timer operation) or external pin T2 (counter operation) as the timer clock input. Setting TR2 allows TL2 to be incremented by the selected input.

Timer 2 has 3 operating modes: capture, autoreload and Baud Rate Generator. These modes are selected by the combination of RCLK, TCLK and CP/$\overline{RL2}$ (T2CON), as described in the Atmel Wireless & Microcontrollers 8-bit Microcontroller Hardware description.

Refer to the Atmel Wireless & Microcontrollers 8-bit Microcontroller Hardware description for the description of Capture and Baud Rate Generator Modes.

In TS80C54/58X2 Timer 2 includes the following enhancements:

- Auto-reload mode with up or down counter
- Programmable clock-output

8.1 Auto-Reload Mode

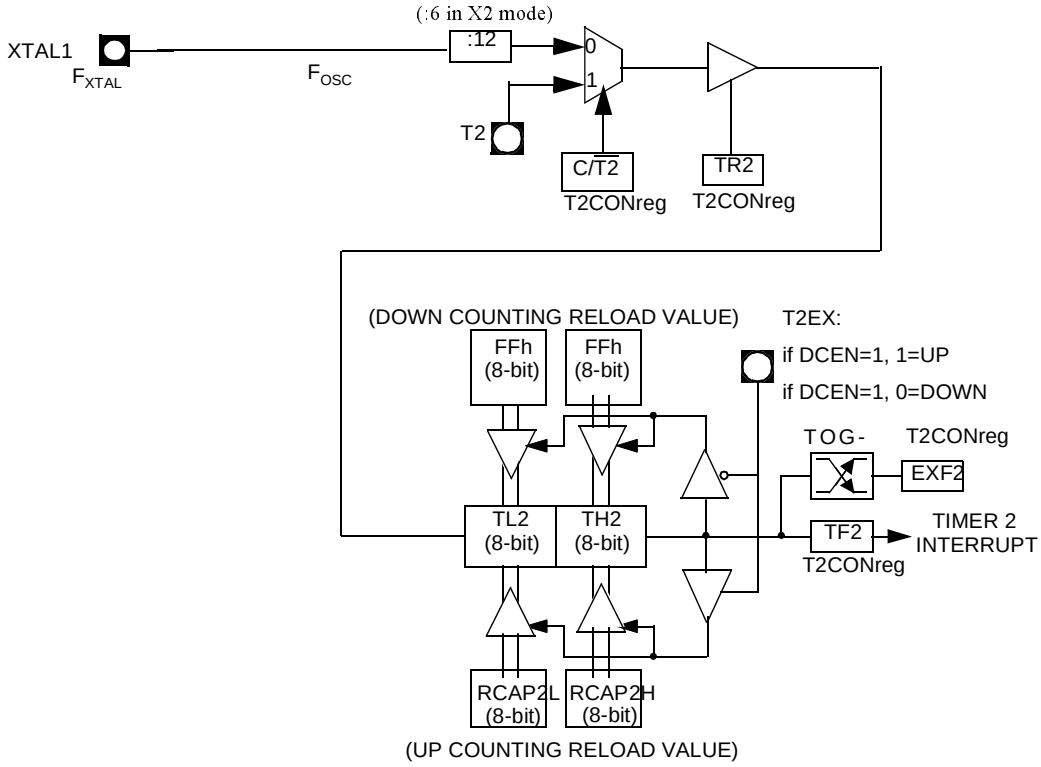
The auto-reload mode configures timer 2 as a 16-bit timer or event counter with automatic reload. If DCEN bit in T2MOD is cleared, timer 2 behaves as in 80C52 (refer to the Atmel Wireless & Microcontrollers 8-bit Microcontroller Hardware description). If DCEN bit is set, timer 2 acts as an Up/down timer/counter as shown in Figure 8-1. In this mode the T2EX pin controls the direction of count.

When T2EX is high, timer 2 counts up. Timer overflow occurs at FFFFh which sets the TF2 flag and generates an interrupt request. The overflow also causes the 16-bit value in RCAP2H and RCAP2L registers to be loaded into the timer registers TH2 and TL2.

When T2EX is low, timer 2 counts down. Timer underflow occurs when the count in the timer registers TH2 and TL2 equals the value stored in RCAP2H and RCAP2L registers. The underflow sets TF2 flag and reloads FFFFh into the timer registers.

The EXF2 bit toggles when timer 2 overflows or underflows according to the the direction of the count. EXF2 does not generate any interrupt. This bit can be used to provide 17-bit resolution

Figure 8-1. Auto-Reload Mode Up/Down Counter (DCEN = 1)



8.1.1 Programmable Clock-Output

In the clock-out mode, timer 2 operates as a 50%-duty-cycle, programmable clock generator (See Figure 8-2) . The input clock increments TL2 at frequency $F_{OSC}/2$. The timer repeatedly counts to overflow from a loaded value. At overflow, the contents of RCAP2H and RCAP2L registers are loaded into TH2 and TL2. In this mode, timer 2 overflows do not generate interrupts. The formula gives the clock-out frequency as a function of the system oscillator frequency and the value in the RCAP2H and RCAP2L registers :

$$Clock-OutFrequency = \frac{F_{osc}}{4 \times (65536 - RCAP2H/RCAP2L)}$$

For a 16 MHz system clock, timer 2 has a programmable frequency range of 61 Hz ($F_{OSC}/2^{16)}$ to 4 MHz ($F_{OSC}/4$). The generated clock signal is brought out to T2 pin (P1.0).

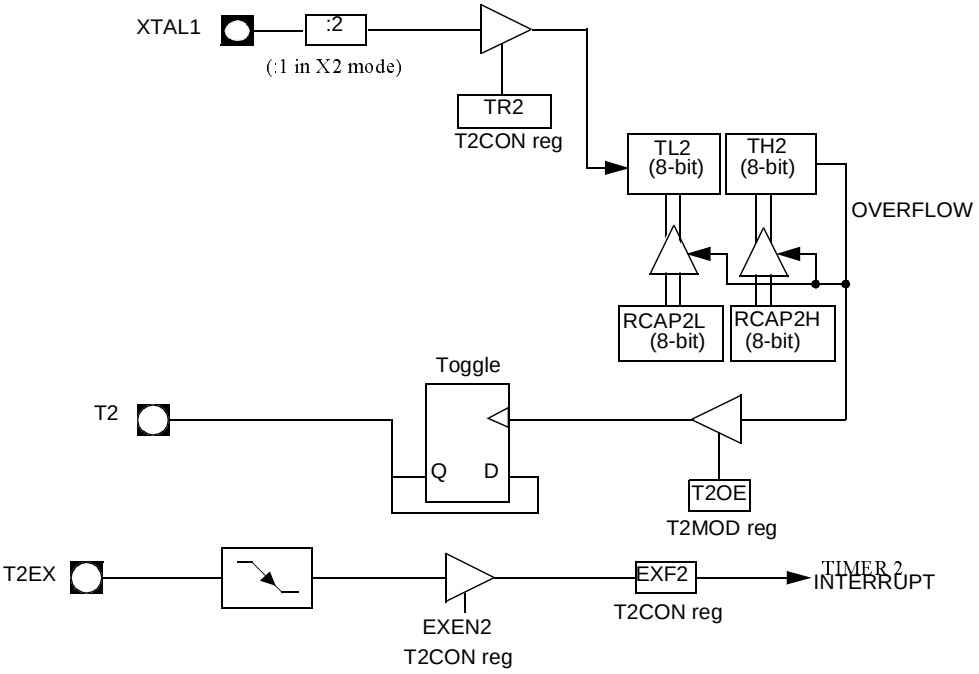
Timer 2 is programmed for the clock-out mode as follows:

- Set T2OE bit in T2MOD register.
- Clear C/$\overline{T2}$ bit in T2CON register.
- Determine the 16-bit reload value from the formula and enter it in RCAP2H/RCAP2L registers.

- Enter a 16-bit initial value in timer registers TH2/TL2. It can be the same as the reload value or a different one depending on the application.
- To start the timer, set TR2 run control bit in T2CON register.

It is possible to use timer 2 as a baud rate generator and a clock generator simultaneously. For this configuration, the baud rates and clock frequencies are not independent since both functions use the values in the RCAP2H and RCAP2L registers.

Figure 8-2. Clock-Out Mode C/$\overline{T2}$ = 0



The following is an example of how to use given addresses to address different slaves:

```
Slave A:    SADDR      1111 0001b
            SADEN      1111 1010b
            Given      1111 0X0Xb

Slave B:    SADDR      1111 0011b
            SADEN      1111 1001b
            Given      1111 0XX1b

Slave C:    SADDR      1111 0010b
            SADEN      1111 1101b
            Given      1111 00X1b
```

The SADEN byte is selected so that each slave may be addressed separately.
For slave A, bit 0 (the LSB) is a don't-care bit; for slaves B and C, bit 0 is a 1. To communicate with slave A only, the master must send an address where bit 0 is clear (e.g. `1111 0000b`).
For slave A, bit 1 is a 1; for slaves B and C, bit 1 is a don't care bit. To communicate with slaves B and C, but not slave A, the master must send an address with bits 0 and 1 both set (e.g. `1111 0011b`).
To communicate with slaves A, B and C, the master must send an address with bit 0 set, bit 1 clear, and bit 2 clear (e.g. `1111 0001b`).

9.1.3 Broadcast Address

A broadcast address is formed from the logical OR of the SADDR and SADEN registers with zeros defined as don't-care bits, e.g.:

```
            SADDR             0101 0110b
            SADEN             1111 1100b
Broadcast =SADDR OR SADEN     1111 111Xb
```

The use of don't-care bits provides flexibility in defining the broadcast address, however in most applications, a broadcast address is FFh. The following is an example of using broadcast addresses:

```
Slave A:    SADDR      1111 0001b
            SADEN      1111 1010b
            Broadcast  1111 1X11b,

Slave B:    SADDR      1111 0011b
            SADEN      1111 1001b
            Broadcast  1111 1X11B,

Slave C:    SADDR=     1111 0010b
            SADEN      1111 1101b
            Broadcast  1111 1111b
```

For slaves A and B, bit 2 is a don't care bit; for slave C, bit 2 is set. To communicate with all of the slaves, the master must send an address FFh. To communicate with slaves A and B, but not slave C, the master can send and address FBh.

9.1.4 Reset Addresses

On reset, the SADDR and SADEN registers are initialized to 00h, i.e. the given and broadcast addresses are `XXXX XXXXb` (all don't-care bits). This ensures that the serial port will reply to any address, and so, that it is backwards compatible with the 80C51 microcontrollers that do not support automatic address recognition.

Table 9-4. PCON Register

Table 9-5. PCON - Power Control Register (87h)

7	6	5	4	3	2	1	0
SMOD1	**SMOD0**	**-**	**POF**	**GF1**	**GF0**	**PD**	**IDL**

Bit Number	Bit Mnemonic	Description
7	SMOD1	**Serial port Mode bit 1** Set to select double baud rate in mode 1, 2 or 3.
6	SMOD0	**Serial port Mode bit 0** Clear to select SM0 bit in SCON register. Set to to select FE bit in SCON register.
5	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
4	POF	**Power-Off Flag** Clear to recognize next reset type. Set by hardware when VCC rises from 0 to its nominal voltage. Can also be set by software.
3	GF1	**General purpose Flag** Cleared by user for general purpose usage. Set by user for general purpose usage.
2	GF0	**General purpose Flag** Cleared by user for general purpose usage. Set by user for general purpose usage.
1	PD	**Power-Down mode bit** Cleared by hardware when reset occurs. Set to enter power-down mode.
0	IDL	**Idle mode bit** Clear by hardware when interrupt or reset occurs. Set to enter idle mode.

Reset Value = 00X1 0000b
Not bit addressable

Power-off flag reset value will be 1 only after a power on (cold reset). A warm reset doesn't affect the value of this bit.

Table 10-3. IP Register

IP - Interrupt Priority Register (B8h)

7	6	5	4	3	2	1	0
-	-	PT2	PS	PT1	PX1	PT0	PX0

Bit Number	Bit Mnemonic	Description
7	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
6	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
5	PT2	**Timer 2 overflow interrupt Priority bit** Refer to PT2H for priority level.
4	PS	**Serial port Priority bit** Refer to PSH for priority level.
3	PT1	**Timer 1 overflow interrupt Priority bit** Refer to PT1H for priority level.
2	PX1	**External interrupt 1 Priority bit** Refer to PX1H for priority level.
1	PT0	**Timer 0 overflow interrupt Priority bit** Refer to PT0H for priority level.
0	PX0	**External interrupt 0 Priority bit** Refer to PX0H for priority level.

Reset Value = XX00 0000b

Bit addressable

11. Idle mode

An instruction that sets PCON.0 causes that to be the last instruction executed before going into the Idle mode. In the Idle mode, the internal clock signal is gated off to the CPU, but not to the interrupt, Timer, and Serial Port functions. The CPU status is preserved in its entirely : the Stack Pointer, Program Counter, Program Status Word, Accumulator and all other registers maintain their data during Idle. The port pins hold the logical states they had at the time Idle was activated. ALE and PSEN hold at logic high levels.

There are two ways to terminate the Idle. Activation of any enabled interrupt will cause PCON.0 to be cleared by hardware, terminating the Idle mode. The interrupt will be serviced, and following RETI the next instruction to be executed will be the one following the instruction that put the device into idle.

The flag bits GF0 and GF1 can be used to give an indication if an interrupt occured during normal operation or during an Idle. For example, an instruction that activates Idle can also set one or both flag bits. When Idle is terminated by an interrupt, the interrupt service routine can examine the flag bits.

The other way of terminating the Idle mode is with a hardware reset. Since the clock oscillator is still running, the hardware reset needs to be held active for only two machine cycles (24 oscillator periods) to complete the reset.

11.1 Power-Down Mode

To save maximum power, a power-down mode can be invoked by software (Refer to Table 9-4., PCON register).

In power-down mode, the oscillator is stopped and the instruction that invoked power-down mode is the last instruction executed. The internal RAM and SFRs retain their value until the power-down mode is terminated. V_{CC} can be lowered to save further power. Either a hardware reset or an external interrupt can cause an exit from power-down. To properly terminate power-down, the reset or external interrupt should not be executed before V_{CC} is restored to its normal operating level and must be held active long enough for the oscillator to restart and stabilize.

Only external interrupts $\overline{INT0}$ and $\overline{INT1}$ are useful to exit from power-down. For that, interrupt must be enabled and configured as level or edge sensitive interrupt input.
Holding the pin low restarts the oscillator but bringing the pin high completes the exit as detailed in Figure 11-1. When both interrupts are enabled, the oscillator restarts as soon as one of the two inputs is held low and power down exit will be completed when the first input will be released. In this case the higher priority interrupt service routine is executed.
Once the interrupt is serviced, the next instruction to be executed after RETI will be the one following the instruction that put TS80C54/58X2 into power-down mode.

13. ONCE™ Mode (ON Chip Emulation)

The ONCE mode facilitates testing and debugging of systems using TS80C54/58X2 without removing the circuit from the board. The ONCE mode is invoked by driving certain pins of the TS80C54/58X2; the following sequence must be exercised:

- Pull ALE low while the device is in reset (RST high) and $\overline{\text{PSEN}}$ is high.
- Hold ALE low as RST is deactivated.

While the TS80C54/58X2 is in ONCE mode, an emulator or test CPU can be used to drive the circuit Table 13-1 shows the status of the port pins during ONCE mode.

Normal operation is restored when normal reset is applied.

Table 13-1. External Pin Status during ONCE Mode

ALE	PSEN	Port 0	Port 1	Port 2	Port 3	XTAL1/2
Weak pull-up	Weak pull-up	Float	Weak pull-up	Weak pull-up	Weak pull-up	Active

16. TS80C54/58X2 ROM

16.1 ROM Structure

The TS80C54/58X2 ROM memory is in three different arrays:

- the code array:16/32 Kbytes.
- the encryption array:64 bytes.
- the signature array:4 bytes.

16.2 ROM Lock System

The program Lock system, when programmed, protects the on-chip program against software piracy.

16.2.1 Encryption Array

Within the ROM array are 64 bytes of encryption array that are initially unprogrammed (all FF's). Every time a byte is addressed during program verify, 6 address lines are used to select a byte of the encryption array. This byte is then exclusive-NOR'ed (XNOR) with the code byte, creating an encrypted verify byte. The algorithm, with the encryption array in the unprogrammed state, will return the code in its original, unmodified form.

When using the encryption array, one important factor needs to be considered. If a byte has the value FFh, verifying the byte will produce the encryption byte value. If a large block (>64 bytes) of code is left unprogrammed, a verification routine will display the content of the encryption array. For this reason all the unused code bytes should be programmed with random values. This will ensure program protection.

16.2.2 Program Lock Bits

The lock bits when programmed according to Table 16-1. will provide different level of protection for the on-chip code and data.

Table 16-1. Program Lock bits

Program Lock Bits				
Security level	**LB1**	**LB2**	**LB3**	**Protection Description**
1	U	U	U	No program lock features enabled. Code verify will still be encrypted by the encryption array if programmed. MOVC instruction executed from external program memory returns non encrypted data.
2	P	U	U	MOVC instruction executed from external program memory are disabled from fetching code bytes from internal memory, $\overline{EA}$ is sampled and latched on reset.

U: unprogrammed
P: programmed

16.2.3 Signature bytes

The TS80C54/58X2 contains 4 factory programmed signatures bytes. To read these bytes, perform the process described in section 8.3.

16.2.4 Verify Algorithm

Refer to 17.3.4

19. Electrical Characteristics

19.1 Absolute Maximum Ratings [1]

Ambiant Temperature Under Bias:
C = commercial0°C to 70°C
I = industrial -40°C to 85°C
Storage Temperature-65°C to + 150°C
Voltage on V_{CC} to V_{SS}-0.5 V to + 7 V
Voltage on V_{PP} to V_{SS}-0.5 V to + 13 V
Voltage on Any Pin to V_{SS}-0.5 V to V_{CC} + 0.5 V
Power Dissipation1 W[2]

1. Stresses at or above those listed under " Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions may affect device reliability.
2. This value is based on the maximum allowable die temperature and the thermal resistance of the package.

19.2 Power consumption measurement

Since the introduction of the first C51 devices, every manufacturer made operating Icc measurements under reset, which made sense for the designs were the CPU was running under reset. In Atmel new devices, the CPU is no more active during reset, so the power consumption is very low but is not really representative of what will happen in the customer system. That's why, while keeping measurements under Reset, Atmel presents a new way to measure the operating Icc:

Using an internal test ROM, the following code is executed:

Label: SJMP Label (80 FE)

Ports 1, 2, 3 are disconnected, Port 0 is tied to FFh, EA = Vcc, RST = Vss, XTAL2 is not connected and XTAL1 is driven by the clock.

This is much more representative of the real operating Icc.

19.3 DC Parameters for Standard Voltage

T_A = 0°C to +70°C; V_{SS} = 0 V; V_{CC} = 5 V ± 10%; F = 0 to 40 MHz.
T_A = -40°C to +85°C; V_{SS} = 0 V; V_{CC} = 5 V ± 10%; F = 0 to 40 MHz.

Table 19-1. DC Parameters in Standard Voltage

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
V_{IL}	Input Low Voltage	-0.5		0.2 V_{CC} - 0.1	V	
V_{IH}	Input High Voltage except XTAL1, RST	0.2 V_{CC} + 0.9		V_{CC} + 0.5	V	
V_{IH1}	Input High Voltage, XTAL1, RST	0.7 V_{CC}		V_{CC} + 0.5	V	
V_{OL}	Output Low Voltage, ports 1, 2, 3 [6]			0.3 0.45 1.0	V V V	I_{OL} = 100 µA[4] I_{OL} = 1.6 mA[4] I_{OL} = 3.5 mA[4]

19.4 DC Parameters for Low Voltage

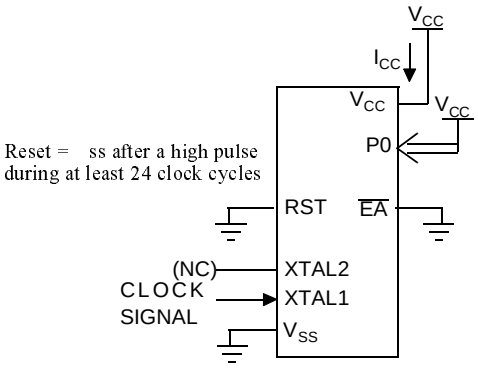
T_A = 0°C to +70°C; V_{SS} = 0 V; V_{CC} = 2.7 V to 5.5 V ± 10%; F = 0 to 30 MHz.
T_A = -40°C to +85°C; V_{SS} = 0 V; V_{CC} = 2.7 V to 5.5 V ± 10%; F = 0 to 30 MHz.

Table 19-2. DC Parameters for Low Voltage

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
V_{IL}	Input Low Voltage	-0.5		0.2 V_{CC} - 0.1	V	
V_{IH}	Input High Voltage except XTAL1, RST	0.2 V_{CC} + 0.9		V_{CC} + 0.5	V	
V_{IH1}	Input High Voltage, XTAL1, RST	0.7 V_{CC}		V_{CC} + 0.5	V	
V_{OL}	Output Low Voltage, ports 1, 2, 3 (6)			0.45	V	I_{OL} = 0.8 mA(4)
V_{OL1}	Output Low Voltage, port 0, ALE, $\overline{PSEN}$ (6)			0.45	V	I_{OL} = 1.6 mA(4)
V_{OH}	Output High Voltage, ports 1, 2, 3	0.9 V_{CC}			V	I_{OH} = -10 µA
V_{OH1}	Output High Voltage, port 0, ALE, $\overline{PSEN}$	0.9 V_{CC}			V	I_{OH} = -40 µA
I_{IL}	Logical 0 Input Current ports 1, 2 and 3			-50	µA	Vin = 0.45 V
I_{LI}	Input Leakage Current			±10	µA	0.45 V < Vin < V_{CC}
I_{TL}	Logical 1 to 0 Transition Current, ports 1, 2, 3			-650	µA	Vin = 2.0 V
R_{RST}	RST Pulldown Resistor	50	90 (5)	200	kΩ	
CIO	Capacitance of I/O Buffer			10	pF	Fc = 1 MHz T_A = 25°C
I_{PD}	Power Down Current		20 (5) 10 (5)	50 30	µA	V_{CC} = 2.0 V to 5.5 V(3) V_{CC} = 2.0 V to 3.3 V(3)
I_{CC} under RESET	Power Supply Current Maximum values, X1 mode: (7)			1 + 0.2 Freq (MHz) @12MHz 3.4 @16MHz 4.2	mA	V_{CC} = 3.3 V(1)
I_{CC} operating	Power Supply Current Maximum values, X1 mode: (7)			1 + 0.3 Freq (MHz) @12MHz 4.6 @16MHz 5.8	mA	V_{CC} = 3.3 V(8)
I_{CC} idle	Power Supply Current Maximum values, X1 mode: (7)			0.15 Freq (MHz) + 0.2 @12MHz 2 @16MHz 2.6	mA	V_{CC} = 3.3 V(2)

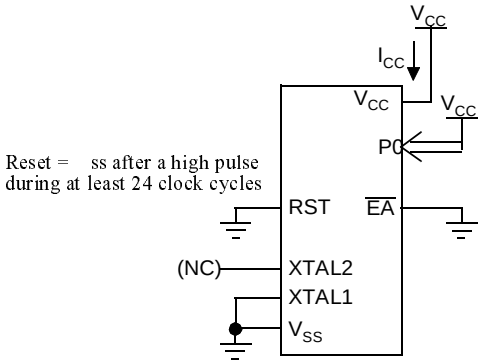
1. I_{CC} under reset is measured with all output pins disconnected; XTAL1 driven with T_{CLCH}, T_{CHCL} = 5 ns (see Figure 19-5.), V_{IL} = V_{SS} + 0.5 V,
   V_{IH} = V_{CC} - 0.5V; XTAL2 N.C.; $\overline{EA}$ = RST = Port 0 = V_{CC}. I_{CC} would be slightly higher if a crystal oscillator used..
2. Idle I_{CC} is measured with all output pins disconnected; XTAL1 driven with T_{CLCH}, T_{CHCL} = 5 ns, V_{IL} = V_{SS} + 0.5 V, V_{IH} = V_{CC} - 0.5 V; XTAL2 N.C; Port 0 = V_{CC}; $\overline{EA}$ = RST = V_{SS} (see Figure 19-3.).
3. Power Down I_{CC} is measured with all output pins disconnected; $\overline{EA}$ = V_{SS}, PORT 0 = V_{CC}; XTAL2 NC.; RST = V_{SS} (see Figure 19-4.).
4. Capacitance loading on Ports 0 and 2 may cause spurious noise pulses to be superimposed on the V_{OL}s of ALE and Ports 1 and 3. The noise is due to external bus capacitance discharging into the Port 0 and Port 2 pins when these pins make 1 to 0 transitions during bus operation. In the worst cases (capacitive loading 100pF), the noise pulse on the ALE line may exceed 0.45V with maxi V_{OL} peak 0.6V. A Schmitt Trigger use is not necessary.

Figure 19-3. I_{CC} Test Condition, Idle Mode



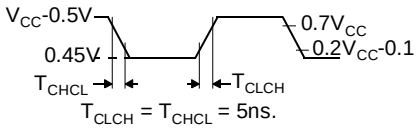
All other pins are disconnected.

Figure 19-4. I_{CC} Test Condition, Power-Down Mode



All other pins are disconnected.

Figure 19-5. Clock Signal Waveform for I_{CC} Tests in Active and Idle Modes



19.5 AC Parameters

19.5.1 Explanation of the AC Symbols

Each timing symbol has 5 characters. The first character is always a “T” (stands for time). The other characters, depending on their positions, stand for the name of a signal or the logical status of that signal. The following is a list of all the characters and what they stand for.

Example:T_{AVLL} = Time for Address Valid to ALE Low.
T_{LLPL} = Time for ALE Low to $\overline{PSEN}$ Low.

T_A = 0 to +70°C (commercial temperature range); V_{SS} = 0 V; V_{CC} = 5 V ± 10%; -M and -V ranges.
T_A = -40°C to +85°C (industrial temperature range); V_{SS} = 0 V; V_{CC} = 5 V ± 10%; -M and -V ranges.
T_A = 0 to +70°C (commercial temperature range); V_{SS} = 0 V; 2.7 V < V_{CC} < 5.5 V; -L range.
T_A = -40°C to +85°C (industrial temperature range); V_{SS} = 0 V; 2.7 V < V_{CC} < 5.5 V; -L range.

Table 19-3. gives the maximum applicable load capacitance for Port 0, Port 1, 2 and 3, and ALE and $\overline{PSEN}$ signals. Timings will be guaranteed if these capacitances are respected. Higher capacitance values can be used, but timings will then be degraded.

Table 19-3. Load Capacitance versus speed range, in pF

	-M	-V	-L
Port 0	100	50	100
Port 1, 2, 3	80	50	80
ALE / $\overline{PSEN}$	100	30	100

Table 19-5., Table 19-8. and Table 19-11. give the description of each AC symbols.

Table 19-6., Table 19-9. and Table 19-12. give for each range the AC parameter.

Table 19-7., Table 19-10. and Table 19-13. give the frequency derating formula of the AC parameter. To calculate each AC symbols, take the x value corresponding to the speed grade you need (-M, -V or -L) and replace this value in the formula. Values of the frequency must be limited to the corresponding speed grade:

Table 19-4. Max frequency for derating formula regarding the speed grade

	-M X1 mode	-M X2 mode	-V X1 mode	-V X2 mode	-L X1 mode	-L X2 mode
Freq (MHz)	40	20	40	30	30	20
T (ns)	25	50	25	33.3	33.3	50

Example:

T_{LLIV} in X2 mode for a -V part at 20 MHz (T = $1/20^{E6}$ = 50 ns):

x= 22 (Table 19-7.)

T= 50ns

T_{LLIV}= 2T - x = 2 x 50 - 22 = 78ns

19.5.4 External Data Memory Characteristics

Table 19-8. Symbol Description

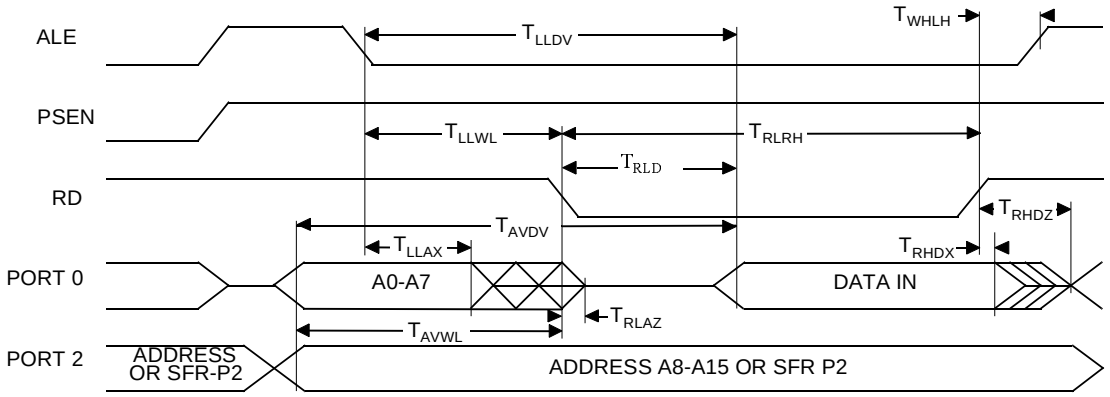
Symbol	Parameter
T_{RLRH}	$\overline{RD}$ Pulse Width
T_{WLWH}	$\overline{WR}$ Pulse Width
T_{RLDV}	$\overline{RD}$ to Valid Data In
T_{RHDX}	Data Hold After $\overline{RD}$
T_{RHDZ}	Data Float After $\overline{RD}$
T_{LLDV}	ALE to Valid Data In
T_{AVDV}	Address to Valid Data In
T_{LLWL}	ALE to $\overline{WR}$ or $\overline{RD}$
T_{AVWL}	Address to $\overline{WR}$ or $\overline{RD}$
T_{QVWX}	Data Valid to $\overline{WR}$ Transition
T_{QVWH}	Data set-up to $\overline{WR}$ High
T_{WHQX}	Data Hold After $\overline{WR}$
T_{RLAZ}	$\overline{RD}$ Low to Address Float
T_{WHLH}	$\overline{RD}$ or $\overline{WR}$ High to ALE high

Table 19-9. AC Parameters for a Fix Clock

Speed	-M 40 MHz		-V X2 mode 30 MHz 60 MHz equiv.		-V standard mode 40 MHz		-L X2 mode 20 MHz 40 MHz equiv.		-L standard mode 30 MHz		Units
Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
T_{RLRH}	130		85		135		125		175		ns
T_{WLWH}	130		85		135		125		175		ns
T_{RLDV}		100		60		102		95		137	ns
T_{RHDX}	0		0		0		0		0		ns
T_{RHDZ}		30		18		35		25		42	ns
T_{LLDV}		160		98		165		155		222	ns
T_{AVDV}		165		100		175		160		235	ns
T_{LLWL}	50	100	30	70	55	95	45	105	70	130	ns
T_{AVWL}	75		47		80		70		103		ns
T_{QVWX}	10		7		15		5		13		ns
T_{QVWH}	160		107		165		155		213		ns
T_{WHQX}	15		9		17		10		18		ns
T_{RLAZ}		0		0		0		0		0	ns
T_{WHLH}	10	40	7	27	15	35	5	45	13	53	ns

19.5.6 External Data Memory Read Cycle

Figure 19-8. External Data Memory Read Cycle



19.5.7 Serial Port Timing - Shift Register Mode

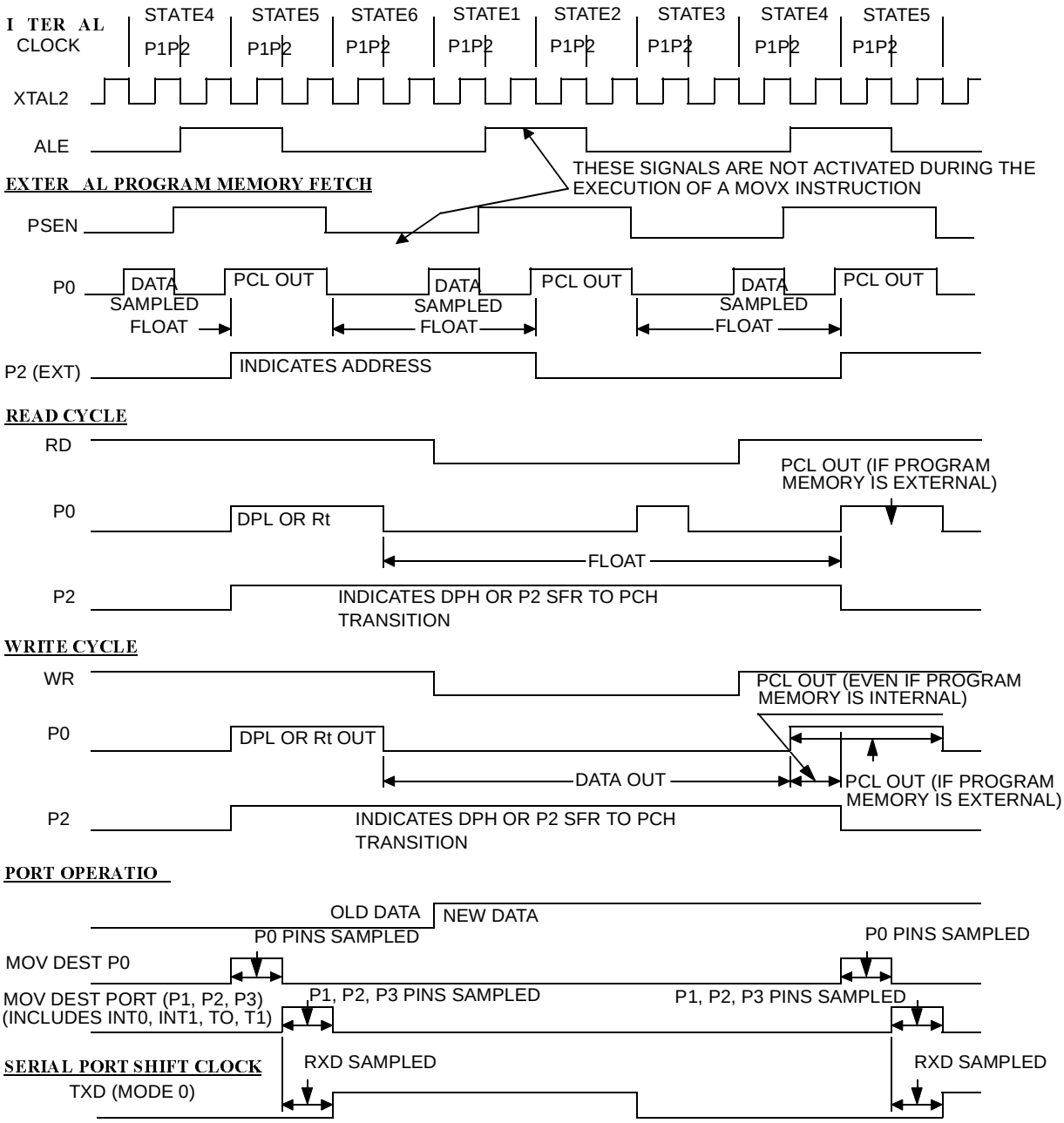
Table 19-11. Symbol Description

Symbol	Parameter
T_{XLXL}	Serial port clock cycle time
T_{QVHX}	Output data set-up to clock rising edge
T_{XHQX}	Output data hold after clock rising edge
T_{XHDX}	Input data hold after clock rising edge
T_{XHDV}	Clock rising edge to input data valid

Table 19-12. AC Parameters for a Fix Clock

Speed	-M 40 MHz		-V X2 mode 30 MHz 60 MHz equiv.		-V standard mode 40 MHz		-L X2 mode 20 MHz 40 MHz equiv.		-L standard mode 30 MHz		Units
Symbol	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	
T_{XLXL}	300		200		300		300		400		ns
T_{QVHX}	200		117		200		200		283		ns
T_{XHQX}	30		13		30		30		47		ns
T_{XHDX}	0		0		0		0		0		ns
T_{XHDV}		117		34		117		117		200	ns

Figure 19-14. Clock Waveforms



This diagram indicates when signals are clocked internally. The time it takes the signals to propagate to the pins, however, ranges from 25 to 125 ns. This propagation delay is dependent on variables such as temperature and pin loading. Propagation also varies from output to output and component. Typically though (T_A=25°C fully loaded) $\overline{RD}$ and $\overline{WR}$ propagation delays are approximately 50ns. The other signals are typically 85 ns. Propagation delays are incorporated in the AC specifications.

Part Number	Supply Voltage	Temperature Range	Package	Packing
TS87C58X2-MCE	5V ±10%	Commercial	VQFP44	Tray
TS87C58X2-VCA	5V ±10%	Commercial	PDIL40	Stick
TS87C58X2-VCB	5V ±10%	Commercial	PLCC44	Stick
TS87C58X2-VCC	5V ±10%	Commercial	PQFP44	Tray
TS87C58X2-VCE	5V ±10%	Commercial	VQFP44	Tray
TS87C58X2-LCA	2.7 to 5.5V	Commercial	PDIL40	Stick
TS87C58X2-LCB	2.7 to 5.5V	Commercial	PLCC44	Stick
TS87C58X2-LCC	2.7 to 5.5V	Commercial	PQFP44	Tray
TS87C58X2-LCE	2.7 to 5.5V	Commercial	VQFP44	Tray
TS87C58X2-MIA	5V ±10%	Industrial	PDIL40	Stick
TS87C58X2-MIB	5V ±10%	Industrial	PLCC44	Stick
TS87C58X2-MIC	5V ±10%	Industrial	PQFP44	Tray
TS87C58X2-MIE	5V ±10%	Industrial	VQFP44	Tray
TS87C58X2-VIA	5V ±10%	Industrial	PDIL40	Stick
TS87C58X2-VIB	5V ±10%	Industrial	PLCC44	Stick
TS87C58X2-VIC	5V ±10%	Industrial	PQFP44	Tray
TS87C58X2-VIE	5V ±10%	Industrial	VQFP44	Tray
TS87C58X2-LIA	2.7 to 5.5V	Industrial	PDIL40	Stick
TS87C58X2-LIB	2.7 to 5.5V	Industrial	PLCC44	Stick
TS87C58X2-LIC	2.7 to 5.5V	Industrial	PQFP44	Tray
TS87C58X2-LIE	2.7 to 5.5V	Industrial	VQFP44	Tray
AT87C58X2-3CSUM	5V ±10%	Industrial & Green	PDIL40	Stick
AT87C58X2-SLSUM	5V ±10%	Industrial & Green	PLCC44	Stick
AT87C58X2-RLTUM	5V ±10%	Industrial & Green	VQFP44	Tray
AT87C58X2-3CSUL	2.7 to 5.5V	Industrial & Green	PDIL40	Stick
AT87C58X2-SLSUL	2.7 to 5.5V	Industrial & Green	PLCC44	Stick
AT87C58X2-RLTUL	2.7 to 5.5V	Industrial & Green	VQFP44	Tray
AT87C58X2-3CSUV	5V ±10%	Industrial & Green	PDIL40	Stick
AT87C58X2-SLSUV	5V ±10%	Industrial & Green	PLCC44	Stick
AT87C58X2-RLTUV	5V ±10%	Industrial & Green	VQFP44	Tray

21. Datasheet Revision History

21.1 Changes from Rev. C 01/01 to Rev. D 11/05

1. Added green product Ordering Information.

21.2 Changes from Rev. D 11/05 to Rev. E 04/06

1. Changed value of AUXR register.